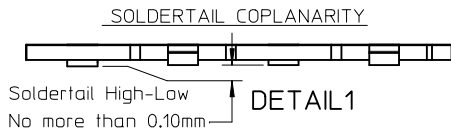
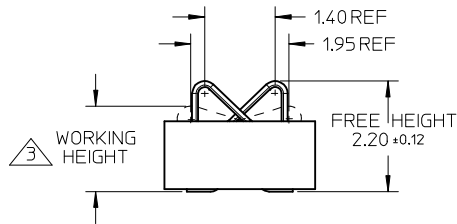
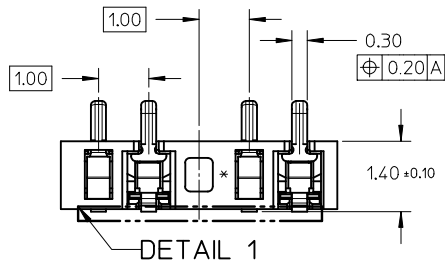
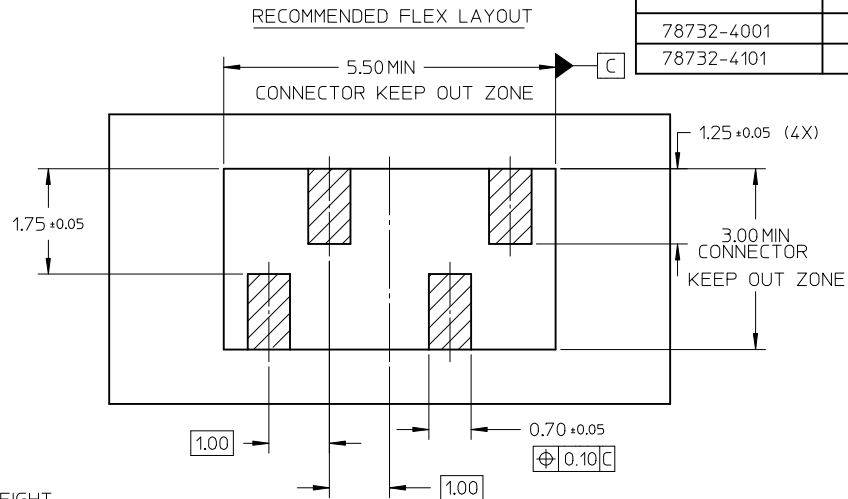
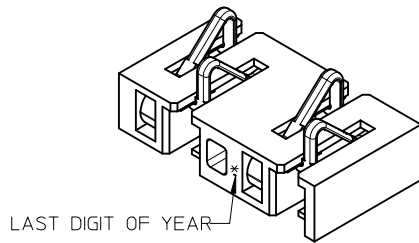
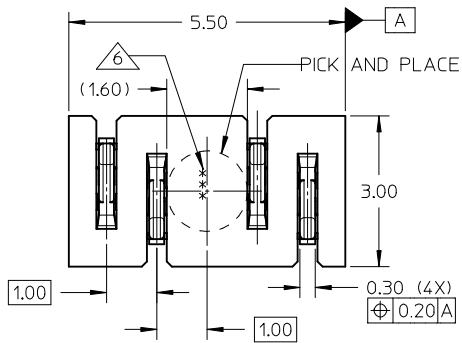
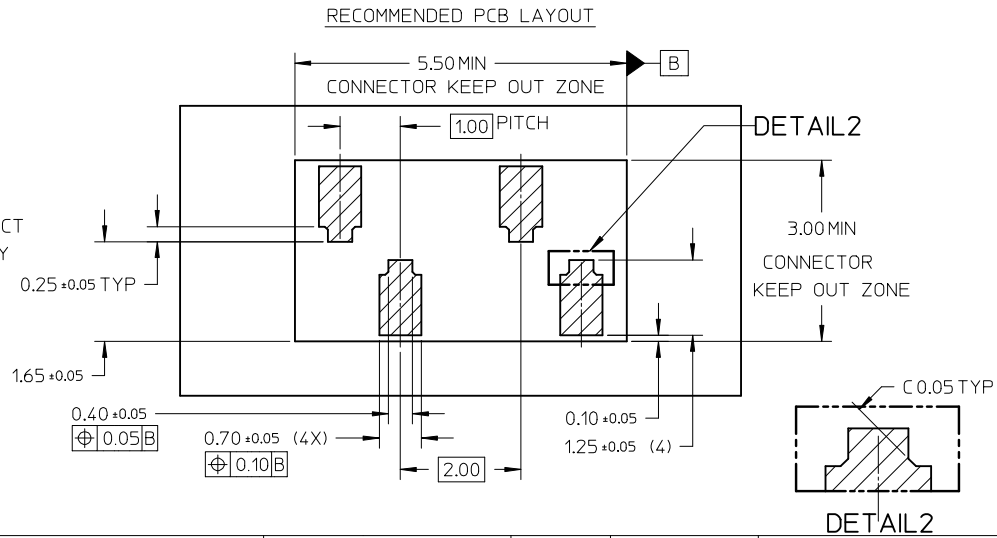
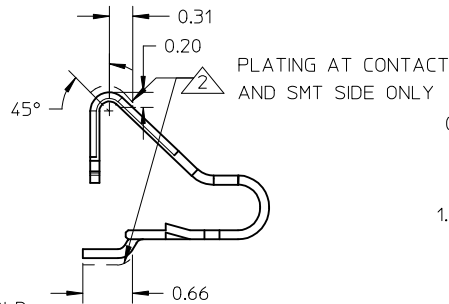


PRODUCT NAME	PACKAGING DRAWING
78732-4001	RPK-78732-401
78732-4101	PK-78732-4101



TERMINAL PLATING SPECIFICATION



NOTES:

- MATERIALS:
HOUSING: LCP,30% GLASS FILLED,COLOUR: BLACK
CONTACT: TITANIUM COPPER TICu
- FINISH:
CONTACT AREA: 0.38 MICRO-METER(15 MICRO-INCH) MIN. GOLD OVER 1.27 MICRO-METER (50 MICRO-INCH) MIN NICKEL UNDERPLATE.
SMT TAIL AREA: 1.27 MICRO-METER (50 MICRO-INCH MIN.) PURE TIN (MATTE) OVER 1.27 MICRO-METER (50 MICRO-INCH) MIN. NICKEL UNDERPLATE.
OTHER AREA PLATING: 1.27 MICRO-METER (50 MICRO-INCH) MIN NICKEL OVERALL

- AT 1.63mm WORKING HEIGHT, FORCE IS 50g +25g/-10g AT LOADING CURVE
- PRODUCT SPECIFICATION SEE PS-78732-1001&RPS-78732-001.
- LAST DIGIT OF THE YEAR TO BE LOCATED.
- DATE CODE TO BE LOCATED.

ENTER DESCRIPTION EC NO: S2015-1521 DRW:ALIN06 CHKD:JZENG APPR:KHLIM	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		$F_A=0$	mm	INCH	DRAWN BY	DATE	TITLE					
		$F_E=0$	4 PLACES ± --- ± ---	KJKOH	2013/05/22	BOARD TO BOARD 4 CIRCUITS COMPRESSION CONNECTOR						
		$F_P=0$	3 PLACES ± --- ± ---	CHECKED BY	DATE	moLEX						
		2 PLACES ± 0.15 ± ---	JESSIECHUA	2013/07/25	DOCUMENT NO. SD-78732-401							
		1 PLACE ± 0.2 ± ---	APPROVED BY	DATE	SHEET NO. 1 OF 1							
		0 PLACE ± --- ± ---	SHONG	2013/08/07	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
		ANGULAR ± 3 °	MATERIAL NO.									
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	SEE TABLE								